

PC/104 AND PC/104 PLUS CONNECTORS
DESCRIPTION OF COMPONENT AND INTENDED APPLICATION

PC/104 and PC/104 Plus connectors are an industry-standard connector system used in PC/104 Embedded PC module stack applications. The PC/104 module stack is designed to use less space and at a lower cost than an equivalent backplane system, by utilising stackthrough connectors to interconnect PC boards within a stack. Standard height between module boards is 0.6"(15.24mm).

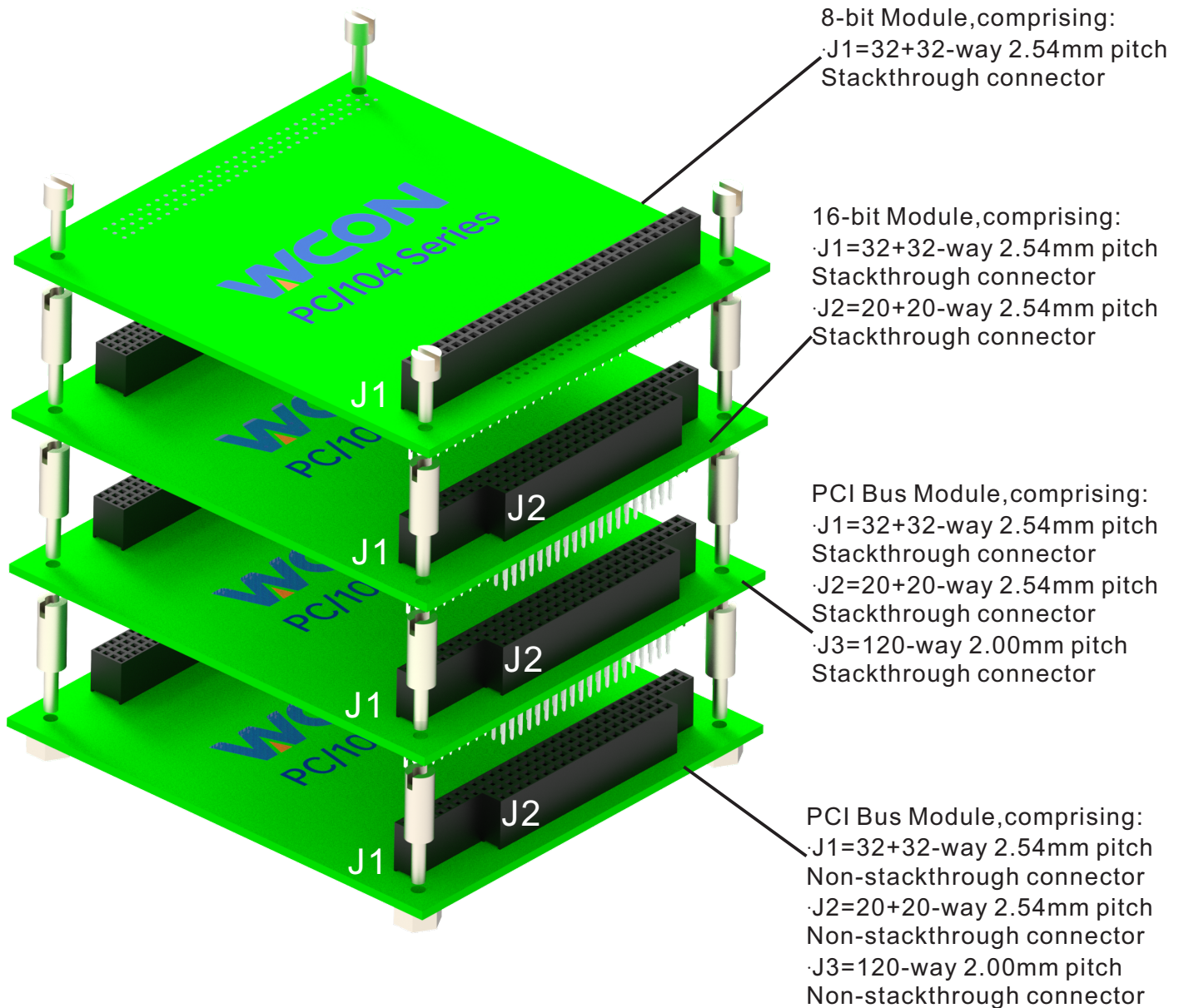
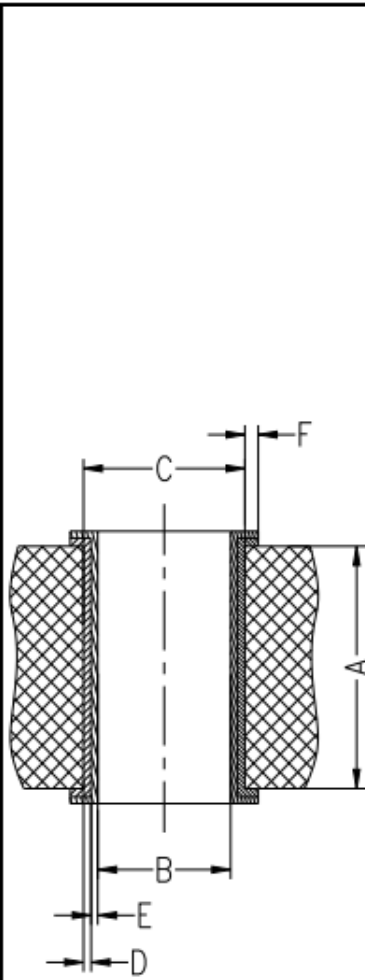


Figure 1-PC/104 Stack

PC/104 connectors are 2.54mm pitch, either 32+32 or 20+20 ways. PC/104 Plus connectors are 2.00mm pitch, 4×30(120)ways. The sockets have a tuning-fork style of contact. Solder or press-fit tail options are available, as are accessories for the range.



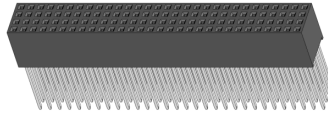
		PC/104 Plus Connector	PC/104 Connector
	Nominal hole	ø0.85mm	ø1.0mm
imm. Sn printed circuit boards			
A	PCB thickness	min. 1.4mm	min. 1.4mm
B	Plated hole	ø0.85+0.09/-0.00mm	ø1.0+0.09/-0.00mm
C	Drill hole	1.0±0.025mm	1.15±0.025mm
D	Cu plating	min. 25µm	min. 25µm
E	imm. Sn plating	max. 1.5µm	max. 1.5µm
F	Annular ring	min. 0.1mm	min. 0.1mm
Ni, Au printed circuit boards			
A	PCB thickness	min. 1.4mm	min. 1.4mm
B	Plated hole	ø0.85+0.09/-0.00mm	ø1.0+0.09/-0.00mm
C	Drill hole	1.0±0.025mm	1.15±0.025mm
D	Cu plating	min. 25µm	min. 25µm
E	Ni, Au plating	0.05~0.2µm Au	0.05~0.2µm Au
		over 2.5~5µm Ni	over 2.5~5µm Ni
F	Annular ring	min. 0.1mm	min. 0.1mm
pure Cu printed circuit boards			
A	PCB thickness	min. 1.4mm	min. 1.4mm
B	Plated hole	ø0.85+0.09/-0.00mm	ø1.0+0.09/-0.04mm
C	Drill hole	1.0±0.025mm	1.15±0.025mm
D	Cu plating	min. 25µm	min. 25µm
E	OSP*	z.B. GLICOAT-SMD (F2)	z.B. GLICOAT-SMD (F2)
		with 0.12~0.15µm	with 0.12~0.15µm
F	Annular ring	min. 0.1mm	min. 0.1mm
HAL Sn printed circuit boards			
A	PCB thickness	min. 1.4mm	min. 1.4mm
B	Plated hole	ø0.85+0.09/-0.02mm	ø1.0+0.09/-0.06mm
C	Drill hole	1.0±0.025mm	1.15±0.025mm
D	Cu plating	min. 25µm	min. 25µm
E	HAL Sn	5~15µm	5~15µm
F	Annular ring	min. 0.1mm	min. 0.1mm

SPECIFICATIONS

Current Rating: 1.5AMP
 Contact Resistance: 20mΩ Max
 Insulation Resistance: 1000MΩ Min
 Withstand Voltage: 500V AC/Minute
 Operation Temperature: -40°C to +105°C
 Contact Material: Phosphor Bronze
 Contact plating: Au over Ni
 Insulator Material: Polyester (UL94V-0)
 Standard: 2293: LCP Black+30%GF
 2293P: PBT Black+30%GF
 Type: S



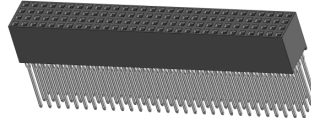
FILE NO: E248993



2293-430SXXDYNTX



CAP2293-G40X



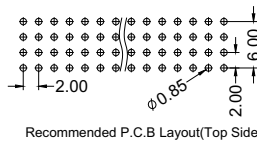
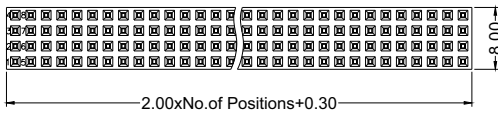
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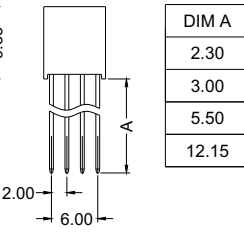
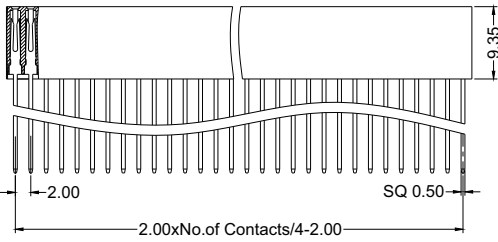
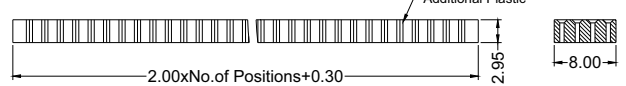
G1230-430CB01

2293	-	4	30	S	XX	D	Y	N	T	X
		Positions Per Row 2~40			Contact plating area G1: 3u" Au/Tin G3: 10u" Au/Tin G4: 15u" Au/Tin	Insulator Material D: LCP				Options 1: Type 1 2: Type 2 3: Type 3

2293-4XXSXXYNTX1

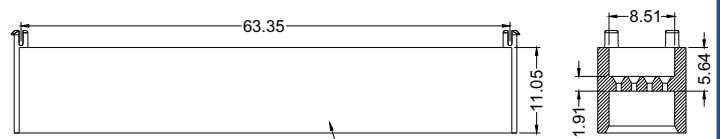


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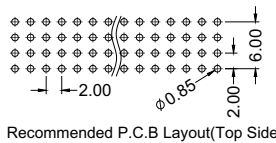
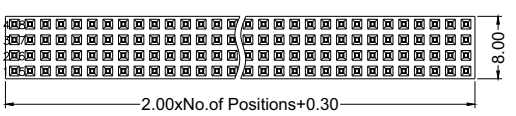
DIM A
2.30
3.00
5.50
12.15

CAP2293-G40X

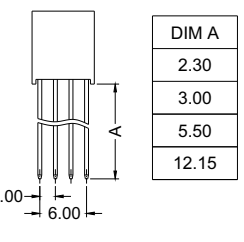
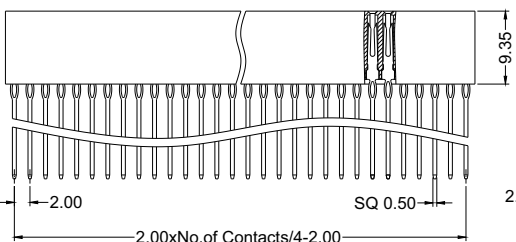
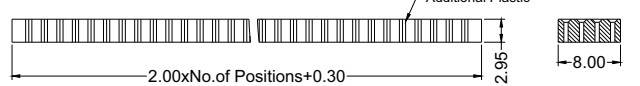


2293P	-	4	30	S	XX	A	Y	N	T	X
		Positions Per Row 2~40			Contact plating area G1: 3u" Au/Tin G3: 10u" Au/Tin G4: 15u" Au/Tin	Insulator Material A: PBT				Options 1: Type 1 2: Type 2 3: Type 3

G1230-430CB01

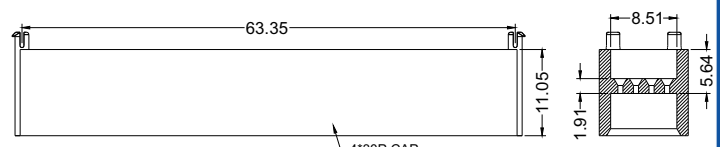


G1230-430CB01



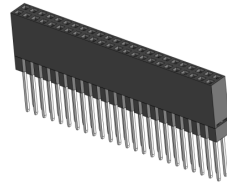
DIM A
2.30
3.00
5.50
12.15

CAP2293-G40X

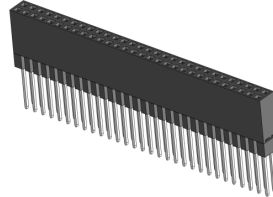


SPECIFICATIONS

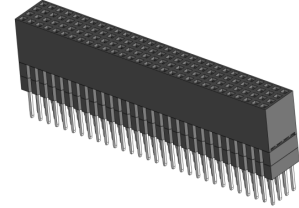
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 Contact Resistance: 20mΩ Max
 Insulation Resistance: 1000MΩ Min
 Withstand Voltage: 500V AC/Minute
 Operation Temperature: -40°C to +105°C
 Contact Material: Phosphor Bronze
 Contact plating: Au over Ni
 Insulator Material: Polyester (UL94V-0)
 Standard: 2263DN2: LCP Black+30%GF
 2183D: PA9T Black+33%GF
 Type: S



2183D-220SXXCYNT1



2183D-232SXXCYNT1



2263DN2-430SXXDYNT1

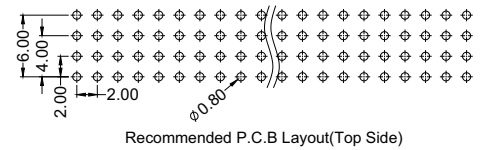
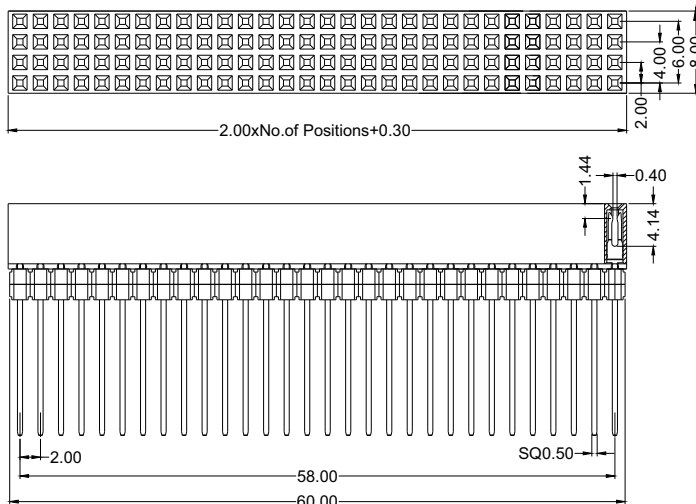
2263DN 2 - 4 30 S XX D Y N T 1

Adding Housing
 2: Add Double Row

Positions
 Per Row
 2~40

Contact plating area
 G1: 3u" Au/Tin
 G3: 10u" Au/Tin
 G4: 15u" Au/Tin

Insulator Material
 D: LCP

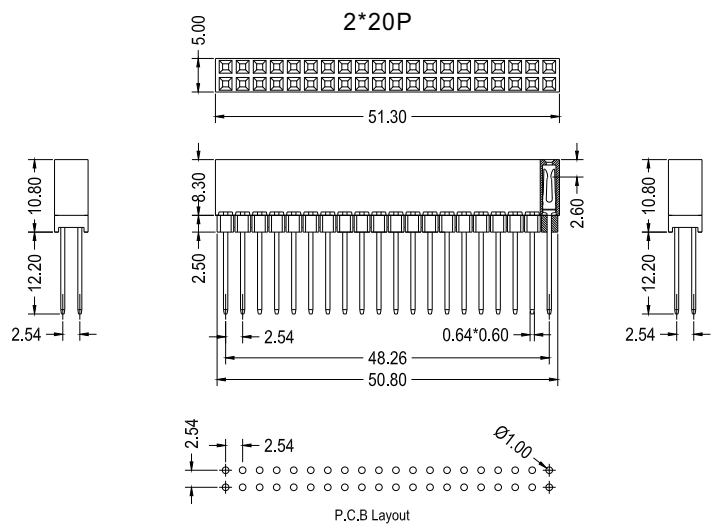
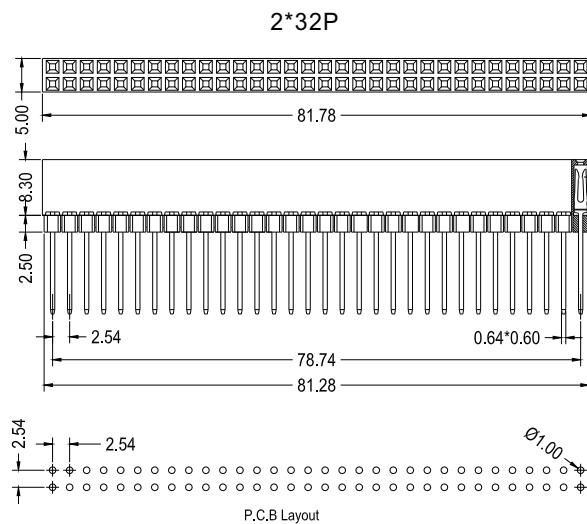


2183D - 2 XX S XX C Y N T 1

Positions
 Per Row
 20,32

Contact plating area
 G1: 3u" Au/Tin
 G3: 10u" Au/Tin
 G4: 15u" Au/Tin

Insulator Material
 C: PA9T

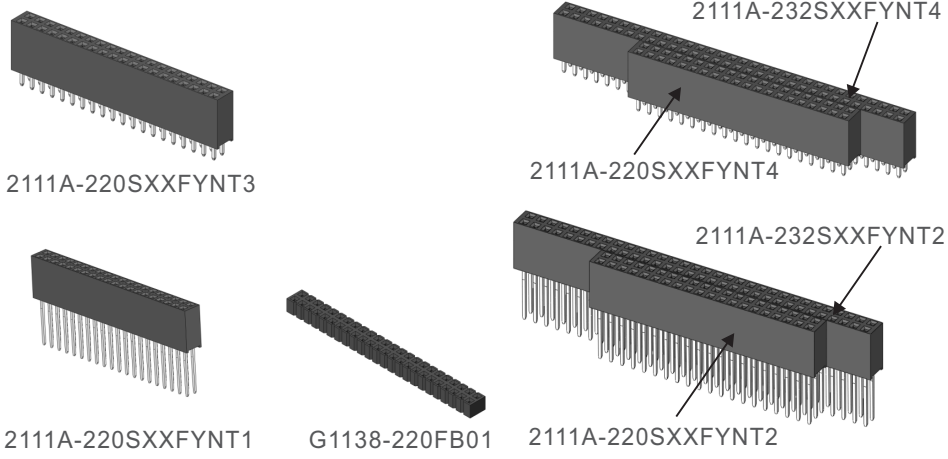


SPECIFICATIONS
 Current Rating: 3.0AMP
 Contact Resistance: 30mΩ Max
 Insulation Resistance: 5000MΩ Min
 Withstand Voltage: 500V AC/Minute
 Operation Temperature: -55°C to +105°C
 Contact Material: Phosphor Bronze
 Contact plating: Au over Ni
 Insulator Material: Polyester (UL94V-0)
 Standard: PPS Black+30%GF
 Type: S

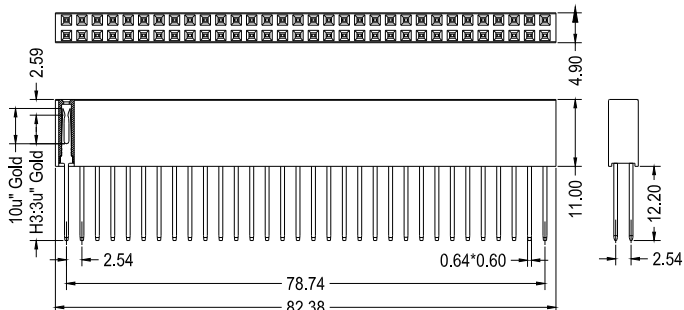


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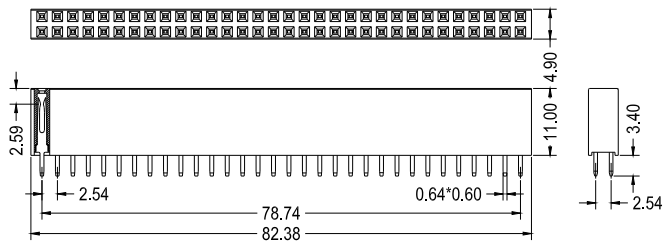
2111A Series, PC/104, 2.54(0.100")



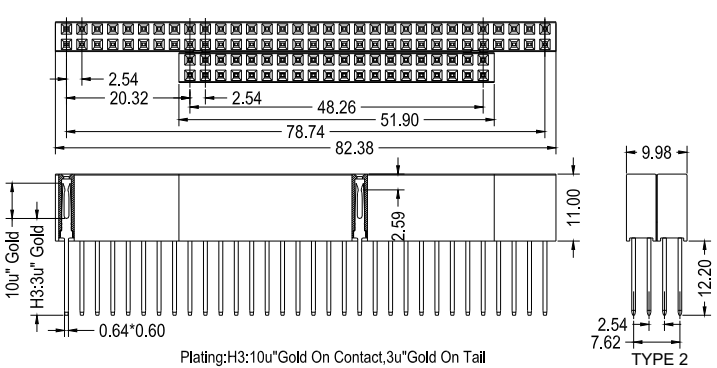
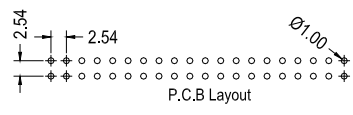
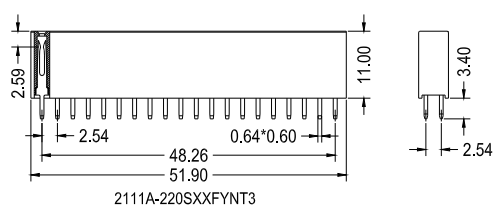
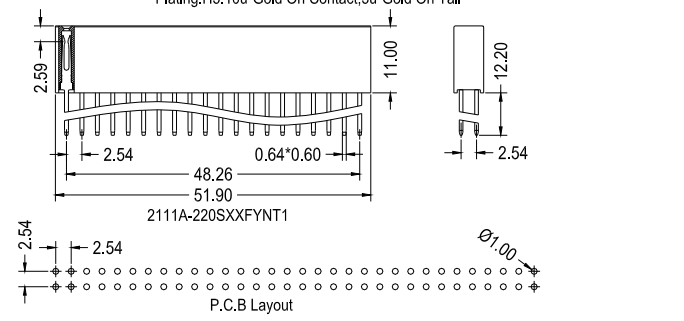
2111A	-	2	<u>XX</u>	S	<u>XX</u>	F	Y	N	<u>X</u>	<u>X</u>
			Positions Per Row 2~32		Contact plating area G1: 3u"Au/Tin G3: 10u"Au/Tin G4: 15u"Au/Tin	Insulator Material F: PPS			Packaging T: Tube A: Tray P: Tube+Cap	Options 1: Type 1 2: Type 2 3: Type 3 4: Type 4



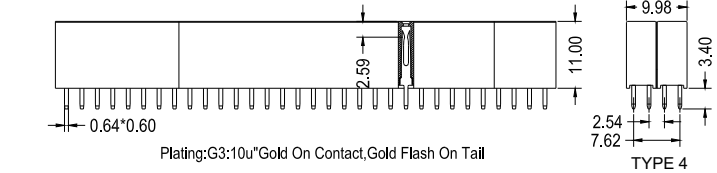
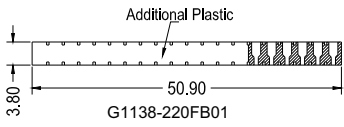
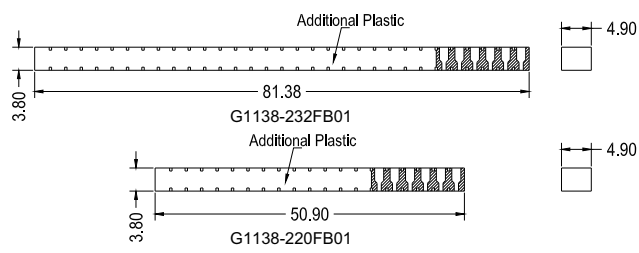
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 Plating: H3: 10u"Gold On Contact, 3u"Gold On Tail



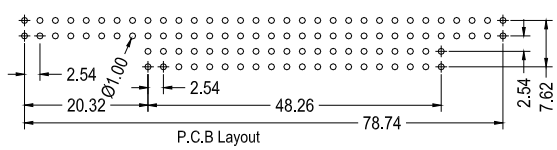
2111A-232SXXFYNT3
 Plating: G3: 10u"Gold On Contact, Gold Flash On Tail



Plating: H3: 10u"Gold On Contact, 3u"Gold On Tail



Plating: G3: 10u"Gold On Contact, Gold Flash On Tail

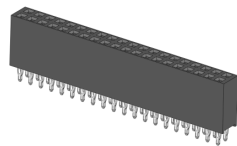


SPECIFICATIONS

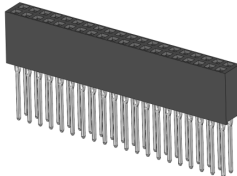
Current Rating: 2.0AMP
 Contact Resistance: 30mΩ Max
 Insulation Resistance: 1000MΩ Min
 Withstand Voltage: 1000V AC/Minute
 Operation Temperature: -55°C to +105°C
 Contact Material: Phosphor Bronze
 Contact plating: Au over Ni
 Insulator Material: Polyester (UL94V-0)
 Standard: PPS Black+30%GF
 Type: S



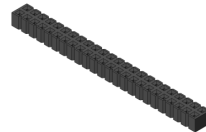
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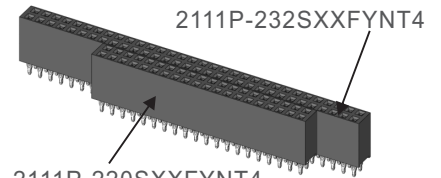
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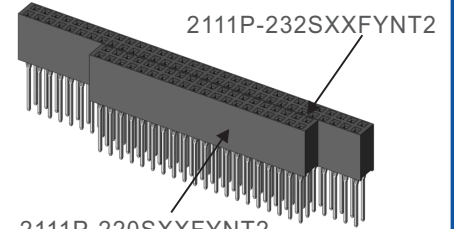
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G1138-220FB01



2111P-220SXXFYNT4



2111P-220SXXFYNT2

2111P	-	2	XX	S	XX	F	Y	N	T	X
			Positions Per Row 2-32		Contact plating area G1: 3u" Au/Tin G3: 10u" Au/Tin G4: 15u" Au/Tin	Insulator Material F: PPS				Options 1: Type 1 2: Type 2 3: Type 3 4: Type 4

